



DEFENSE LOGISTICS AGENCY
LAND AND MARITIME
POST OFFICE BOX 3990
COLUMBUS, OH 43218-3990

May 22, 2013

Ms. Eve Crain
Westak of Oregon
3941 24th Avenue
Forest Grove, OR 97116-2208

Dear Ms. Crain:

RE: Notice of Qualification; MIL-PRF-31032/1, /2; FSC 5998; CAGE Code 65745; VQ (VQE-13-026434) / CN039567

Qualification of products is granted as a result of successful qualification testing to Military Performance Specification MIL-PRF-31032, Printed Circuit Board/Printed Wiring Board, and associated specification MIL-PRF-31032/1 and /2. The capabilities qualified for each base material and slash sheet indicated below shall be listed on Qualified Manufacturers List QML-31032. The effective date of this qualification is May 22, 2013.

MANUFACTURER	PLANT LOCATIONS	CAGE CODE: 65745
Westak of Oregon 3941 24th Avenue Forest Grove, OR 97116-2208	Same Address as Manufacturer	PHONE #: 503-359-3593 FAX #: 503-357-5332 EMAIL: ecrain@westak.com
Specification: MIL-PRF-31032/1, MIL-PRF-31032/2 Qualification Letters: VQE-13-026434 Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant Max. Panel Size: 18" x 24" Max. Number of Layers: 10 Max. Board Thickness: 0.110" Min. Hole Size: 0.020" Drilled Plated-Through Hole Before Plating Aspect Ratio: 5.5:1 Through-Hole Min. Conductor Width/Space: 0.005 "/0.005" Hole Preparation: Permanganate Desmear, Plasma Desmear/Etchback Hole Wall Conductive Coating: Electroless Copper		

Copper Plating: Direct Current Plate
Solder Resist: Liquid Photoimageable
Finish System: HASL, ENIG
Controlled Impedance: Single Sided, Differential

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2
Qualification Letters: VQE-13-026434
Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
Max. Panel Size: 18" x 24"
Max. Number of Layers: 10
Max. Board Thickness: 0.110"
Min. Hole Size: 0.020" Drilled Plated-Through Hole Before Plating
Aspect Ratio: 5.5:1 Through-Hole
Min. Conductor Width/Space: 0.005 "/0.005"
Hole Preparation: Permanganate Desmear, Plasma Etchback/Desmear
Hole Wall Conductive Coating: Electroless Copper
Copper Plating: Direct Current Plate
Solder Resist: Liquid Photoimageable
Finish System: HASL, ENIG
Controlled Impedance: Single Sided, Differential

Test report number 31032-3858-13 has been assigned to your test data. This qualification is based on your MIL-PRF-31032 certification and is subject to the conditions stated below:

1. A listing on the Qualified Manufacturers List (QML) does not guarantee acceptance of the product(s) in any future purchase.
2. QML listing does not constitute a waiver of any requirements of the specification or of the provisions of any contract.
3. Advertising of qualification information is permitted. Permission to use such information for advertising or publicity purposes is granted provided that such publicity or advertising

does not state or imply that the product(s) is the only product of that type qualified or that the Department of Defense in any way recommends or endorses the manufacturer's product.

4. The listing applies only to products produced in the plant(s) specified in this letter of notification of qualification and applies to future amendments or revisions of the specification, unless otherwise notified.
5. The listing applies only to materials and manufacturing construction techniques identical to or covered by that (those) qualified. The qualifying activity must be advised in advance of any change to the materials and manufacturing construction techniques. Failure to notify the qualifying activity of any change to the materials and manufacturing construction techniques is cause for removal from the QML.

Manufacturers are required to inform this Office immediately if a failure occurs during PCI testing, if production of this qualification is discontinued, or prior to issuance of a GIDEP Alert and/or Problem Advisory on their QML products. If you have any questions, please contact Mr. Robert Puckett, (614) 692-0625 or vqe.rp@dla.mil.

Sincerely,

/SIGNED/

JOSEPH GEMPERLINE
Chief
Sourcing and Qualification Division